

THERMAL PERFORMANCE			
PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-Ambient Thermal Resistance	$R_{\theta JA}$	55	°C/W
Junction-to-lead thermal resistance	$R_{\theta JL}$	18	°C/W

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage per diode ⁽¹⁾	$I_F = 2\text{A}, T_J = 25^\circ\text{C}$	V_F	-	1.3	V
Reverse current @ rated V_R per diode ⁽²⁾	$T_J = 25^\circ\text{C}$	I_R	-	5	μA
	$T_J = 125^\circ\text{C}$		-	50	μA
Junction capacitance	1 MHz, $V_R = 4.0\text{V}$	C_J	50	-	pF
Reverse recovery time	$I_F = 0.5\text{A}, I_R = 1.0\text{A}$ $I_{RR} = 0.25\text{A}$	t_{rr}	-	150	ns
					ns
					ns
					ns
			-	250	ns
			-	500	ns
			ns		

Notes:

1. Pulse test with $PW = 0.3\text{ ms}$
2. Pulse test with $PW = 30\text{ ms}$

ORDERING INFORMATION					
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX(*)	PACKAGE	PACKING
RS2x (Note 1)	H	R5	G	SMB	850 / 7" Plastic reel
		R4		SMB	3,000 / 13" Paper reel
		M4		SMB	3,000 / 13" Plastic reel

Note:

1. "x" defines voltage from 50V (RS2A) to 1000V (RS2M)
- *: Optional available

EXAMPLE P/N					
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
RS2JHR5G	RS2J	H	R5	G	AEC-Q101 qualified Green compound

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig1. Forward Current Derating Curve

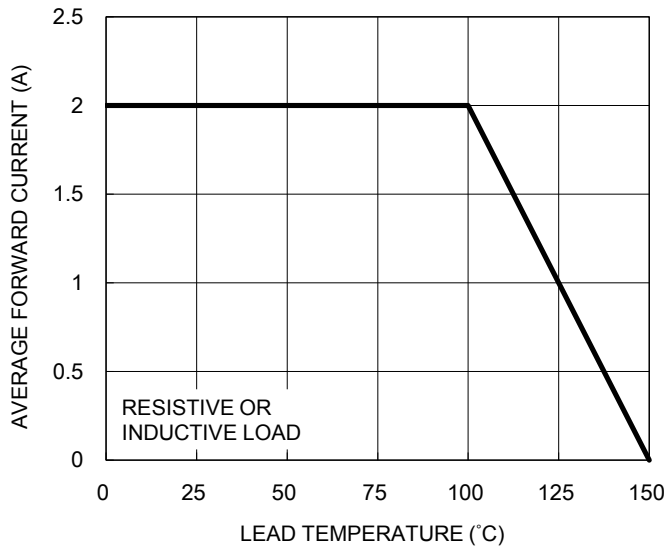


Fig2. Typical Junction Capacitance

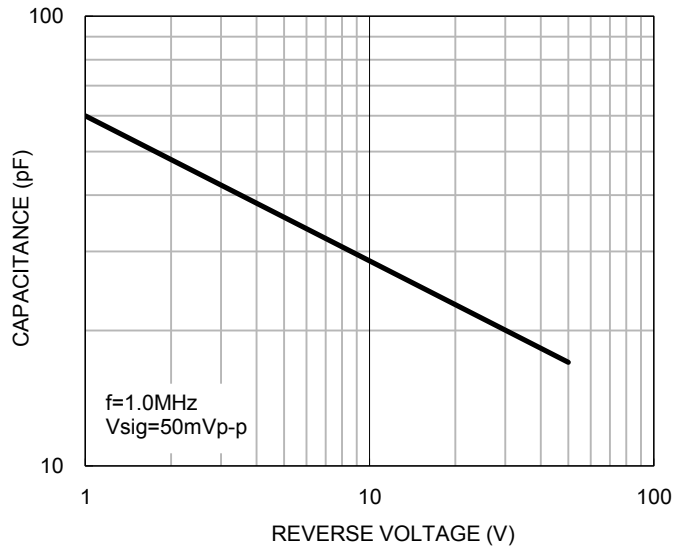


Fig3. Typical Reverse Characteristics

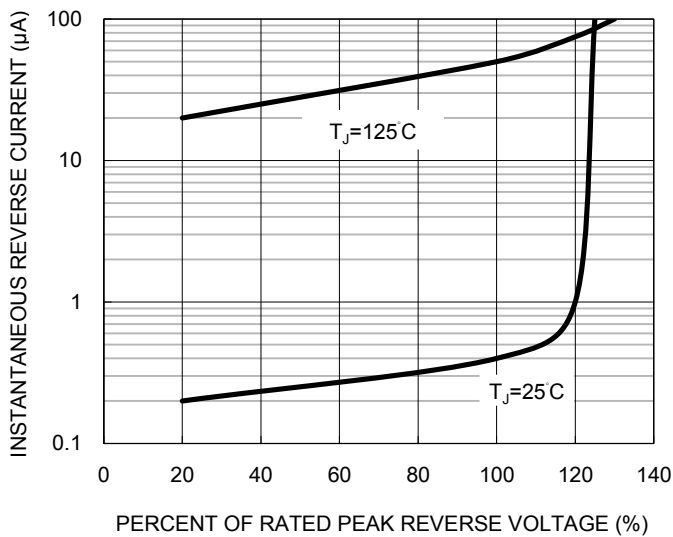


Fig4. Typical Forward Characteristics

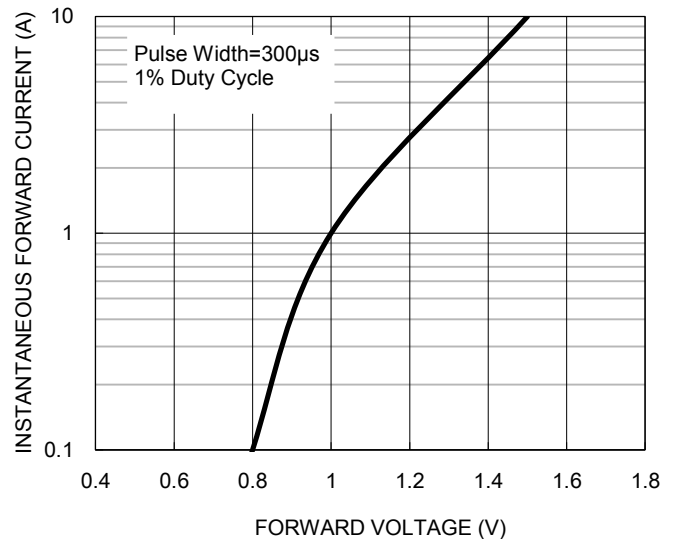


Fig5. Maximum Non-repetitive Forward Surge Current

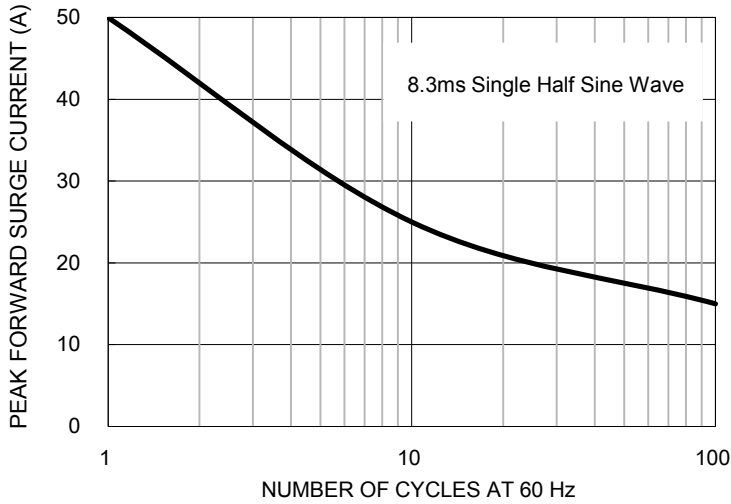
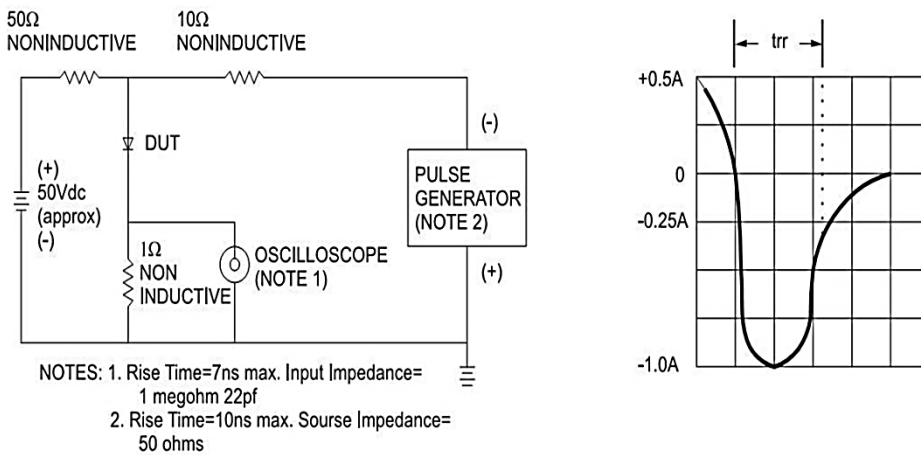
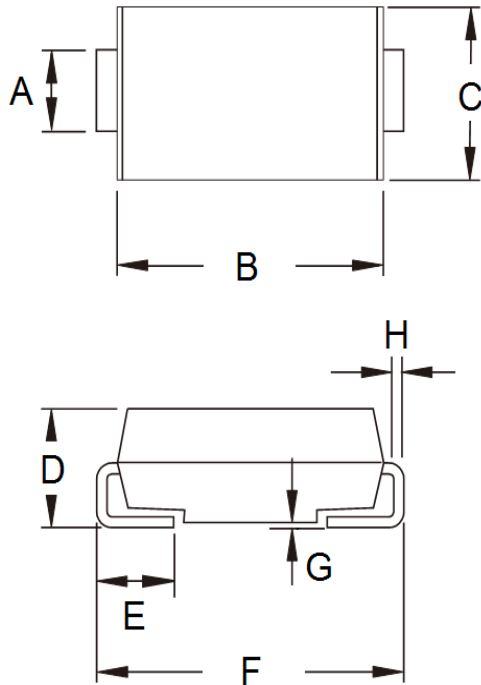


Fig6. Reverse Recovery Time Characteristic And Test Circuit Diagram



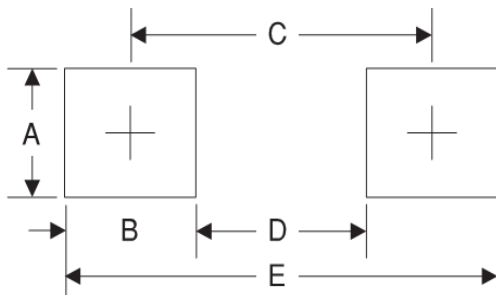
PACKAGE OUTLINE DIMENSIONS

DO-214AA (SMB)



DIM.	Unit (mm)		Unit (inch)	
	Min	Max	Min	Max
A	1.95	2.20	0.077	0.087
B	4.05	4.60	0.159	0.181
C	3.30	3.95	0.130	0.156
D	1.95	2.65	0.077	0.104
E	0.75	1.60	0.030	0.063
F	5.10	5.60	0.201	0.220
G	0.05	0.20	0.002	0.008
H	0.15	0.31	0.006	0.012

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	2.3	0.091
B	2.5	0.098
C	4.3	0.169
D	1.8	0.071
E	6.8	0.268

MARKING DIAGRAM



P/N = Marking Code
 G = Green Compound
 YW = Date Code
 F = Factory Code

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